HP Z8 G5 Workstation Desktop PC



- 1. Integrated Front Handle
- 2. Power Button
- 3. HDD Activity LED
- 4. Headphone/microphone combo

Front View

- Front I/O:
 4 SuperSpeed USB Type-A 5 Gbps signaling rate [left-most Type-A ports supports BC1.2 (Battery Charging)]
- 6. SD Card Reader
- 7. 2x External 5.25" bay¹
- 8. 9.5mm Optical Drive Bay

¹Only 1 external 5.25" drive configurable from factory



Internal View

- 1. 2 Intel® Xeon® Processors (Sapphire Rapids-Scalable)
- 2. 16 DIMM slots for DDR5 ECC Memory 8 DIMMs per installed processor
- •Slot 1: PCIe x16 Gen4
 - •Slot 2: PCIe x16 Gen4 Available ONLY when 2nd processor is 8. 2 External 5.25" bays and Slimline Optical Drive installed
 - •Slot 3: PCIe x4 Gen3
 - •Slot 4: PCIe x16 Gen5
 - •Slot 5: PCIe x8 Gen3
 - •Slot 6: PCIe x16 Gen3 Available ONLY when 2nd processor is installed
 - •Slot 7: PCIe x4 Gen3
- 4. 2 PCIe x8 Gen4 configurable with 4 Z Turbo M.2 SSDs (2nd slot available ONLY when 2nd processor is installed)

- 5. 6 SATA ports
- 6. 3 Internal USB Ports (1 single USB2.0 port, 1 dual USB2.0 port, 1 USB3.0 port (for the SD card reader))
- 7. 4 Internal 3.5" bays
- 9. 1 Internal NVMe connector to front removable M.2 carrier





Rear View

- 1. Choice of 1125W, 1450W or 1700W, 90% Efficient Power Supplies
- 2. Rear Power Button
- 3. Audio in/out
- 4. 6 SuperSpeed USB Type-A 5 Gbps signaling rate

- 5. 2 RJ-45 integrated LAN ports (1 GbE AMT, 1GbE)
- 6. 2 10GbE LAN ports (optional)
- 7. Integrated Rear Handle

Form Factor

Tower

Operating Systems

Preinstalled:

- Windows 11 Pro for Workstations²
- Windows 11 Pro for Workstations (preinstalled with Windows 10 Pro for Workstations Downgrade),^{2,3}
- Ubuntu 22.04 LTS⁴
- HP Linux®-ready (minimal OS ready for customer OS installation)⁵

License Only:

 Red Hat® Enterprise Linux® Desktop Workstation (includes paper license with 1 year support; no preinstalled OS)⁶

Supported:

- Windows 11, version 22H2, 21H2²
- Windows 10, version 22H2, 21H2²
- Red Hat® Enterprise Linux® Workstation 8 & 96



Overview

- SUSE Linux® Enterprise Desktop 15⁶
- Ubuntu 20.04 & 22.04 LTS⁵

Web-supported only:

- Windows 11 Enterprise^{2,1}
- Windows 10 Enterprise^{2,1}
- ¹ Windows Enterprise sold separately and requires that customer have an enterprise license from Microsoft.
- ² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- ³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.
- ⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.
- ⁵A certified preloaded version of Ubuntu® 20.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for upgrades.
- ⁶For detailed Linux[®] OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282



Overview

Processors

			Frequency (GHz)			Max Memory Speed (MT/s)	
Name ¹	Cores	Threads	Base Clock Speed	Intel® Turbo Boost Max Single-Core Frequency ²	Cache (MB)	1 DIMM per Channel	TDP (W)
Intel® Xeon® Gold 6448Y	32	64	2.1	4.1	60	4800	225
Intel® Xeon® Gold 6438Y+	32	64	2.0	4.0	60	4800	205
Intel® Xeon® Gold 6430	32	64	2.1	3.4	60	4400	270
Intel® Xeon® Gold 5420+	28	56	2.0	4.1	52.5	4400	205
Intel® Xeon® Gold 6442Y	24	48	2.6	4.0	60	4800	225
Intel® Xeon® Gold 5418Y	24	48	2.0	3.8	45	4400	185
Intel® Xeon® Silver 4416+	20	40	2.0	3.9	37.5	4000	165
Intel® Xeon® Gold 6444Y	16	32	3.6	4.1	45	4800	270
Intel® Xeon® Gold 6426Y	16	32	2.5	4.1	37.5	4800	185
Intel® Xeon® Gold 5416S	16	32	2.0	4.0	30	4400	150
Intel® Xeon® Silver 4410Y	12	24	2.0	3.9	30	4000	150
Intel® Xeon® Gold 6434	8	16	3.7	4.1	22.5	4800	195
Intel® Xeon® Gold 5415+	8	16	2.9	4.1	22.5	4400	150

Notes:

- 4th Gen Xeon -SP processors all feature Intel® vPro® Technology³
- 4th Gen Xeon -SP processors all support Hyper-Threading
- 4th Gen Xeon -SP processors do not offer integrated graphics

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Intel Turbo Boost Max (ITBM) performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.



Overview

Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro

Color Black **Convertibility** No

Expansion Slots •Slot 1: PCle x16 Gen4

(see system board •Slot 2: PCIe x16 Gen4 - Available ONLY when 2nd processor is installed

•Slot 3: PCIe x4 Gen3
•Slot 4: PCIe x16 Gen5
•Slot 5: PCIe x8 Gen3

•Slot 6: PCIe x16 Gen3 - Available ONLY when 2nd processor is installed

•Slot 7: PCIe x4 Gen3

Expansion Bays 4 internal 3.5" bays (All 4 include acoustic dampening rail assemblies)

(see storage section for more details) 2 external 5.25" bays (175mm depth limit) 1 dedicated 9.5mm slim optical disk drive bay

Front I/O: 4 SuperSpeed USB Type-A 5 Gbps signaling rate, 1 headphone/microphone combo, SD card

reader (optional). [left-most Type-A ports supports BC1.2 (Battery Charging)]

Internal I/O [5] 3 Internal USB ports and 6 SATA ports.

Rear I/O Audio in/out, 6 SuperSpeed USB Type-A 5 Gbps signaling rate, 2 RJ-45 integrated LAN ports (1 GbE AMT,

1GbE)

Optional I/O 2 10GbE LAN ports

On-board RAID Support SATA RAID O Striped Array

SATA RAID 1 Mirrored Array SATA RAID 10 Striped/Mirrored SATA RAID 5 Parity Array

Chassis Dimensions

(H x W x D)

Footprint:

H: 17.5" [444.5mm] W: 8.5" [215.9mm]

D: 21.7" [551.2mm] (measured to the rear of service panel)

Maximum:

H: 17.5" [444.5mm] W: 8.5" [215.9mm]

D: 21.85" [555.2mm] (measured to the embossment for the rear chassis fans)

Packaged Dimensions H: 25" (636mm)

W: 13.1" (332mm) D: 28.9" (734mm)

Palletization Profile 4 units x 3 layers = 12 units per pallet

1200x1000x2034mm (pallet included)

Rack Dimensions 5U

Weight Exact weights depend upon configuration (System weight only).

Minimum: 22.5kg (49.6lbs.) Typical: 24.3kg (53.7lbs.) Maximum: 33.8kg (74.6lbs.)

Temperature Operating: 5° to 40°C (40° to 104°F)¹

Non-operating: -40° to 60°C (-40° to 140°F)

¹40°C has been validated for configs up to 2x 270W CPU (Intel Xeon Gold 6430), 2x NVIDIA® RTX A4000

graphics cards, 8x64GB RAM, 4x 2TB M.2 storage, 2x 2TB HDD storage, and 1125W PSU

Humidity Operating: 0perating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90%, non-condensing, 35° C maximum wet bulb

Maximum Altitude (non-pressurized)⁶

Operating: 3,048m (10,000ft) Non-operating: 9,144m (30,000ft)

NOTE: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1°C (1.8°F)

per 305 m (1,000 feet) elevation increase

Power Supply Choice of 90% Efficient Power Supplies:

1125W1450W

• 1700W

NOTE:

Not all configurations are supported on all power supplies. Configuration support depends on total system power budget and having sufficient number or type of PCIe supplemental power connectors. Confirm power supply and configuration support using configurator on hp.com.

- 1125W supports up to 600W of auxiliary graphics power (dependent on system configuration)
- 1450W supports up to 600W of auxiliary graphics power (dependent on system configuration)
- 1700W supports up to 600W of auxiliary graphics power (dependent on system configuration)

NOTE: updating graphics after purchase may require additional power distribution cables and/or auxiliary graphics adapters to support the new graphics configuration.

Workstation ISV Certifications See the latest list of certifications at

http://www.hp.com/united-states/campaigns/workstations/partnerships.html

Chipset Intel® C741 chipset

Memory 16 DIMM slots, supporting up to 1TB, DDR5 4800 MT/s speed depending on the system configuration



Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	4th Generation Intel® Xeon® Scalable Processors				
	Intel® Xeon® Gold 6448Y	Υ	Υ	6Y3A1AA	1
	Intel® Xeon® Gold 6444Y	Υ	Υ	6Y3A8AA	1
	Intel® Xeon® Gold 6442Y	Υ	Υ	6Y3A5AA	1
	Intel® Xeon® Gold 6438Y+	Υ	Υ	6Y3A2AA	1
	Intel® Xeon® Gold 6434	Υ	Υ	6Y3B2AA	1
	Intel® Xeon® Gold 6430	Υ	Υ	6Y3A3AA	1
	Intel® Xeon® Gold 6426Y	Υ	Υ	6Y3A9AA	1
	Intel® Xeon® Gold 5420+	Υ	Υ	6Y3A4AA	1
	Intel® Xeon® Gold 5418Y	Υ	Υ	6Y3A6AA	1
	Intel® Xeon® Gold 5416S	Υ	Υ	6Y3B0AA	1
	Intel® Xeon® Gold 5415+	Υ	Υ	6Y3B3AA	1
	Intel® Xeon® Silver 4416+	Υ	Υ	6Y3A7AA	1
	Intel® Xeon® Silver 4410Y	Υ	Υ	6Y3B1AA	1

NOTE 1: When ordering two processors, the second processor must be the same as the first. Intel processor numbers are not a measurement of higher performance. Processor numbers differentiate features within each processor family, not across different processor families.

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
	1TB 7200RPM SATA 3.5in Enterprise HDD	Υ	Υ	WOR10AA
	2TB 7200RPM SATA 3.5in Enterprise HDD	Υ	Υ	2Z274AA
	4TB 7200RPM SATA 3.5in Enterprise HDD	Υ	Υ	K4T76AA/AT
	8TB 7200RPM SATA 3.5in Enterprise HDD	Υ	Υ	2Z273AA
	12TB 7200RPM SATA-6G 3.5in Enterprise HDD	Υ	Y	5S461AA
PCIe Solid State				
Drives	Z Turbo 512GB 2280 PCle-4x4 TLC SSD	Υ	Υ	38T80AA
	Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD	Υ	Υ	38T81AA
	Z Turbo 512GB 2280 PCle-4x4 TLC Z8 Kit SSD	N	Υ	360H7AA
	Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z8 Kit SSD	N	Υ	360H2AA
	Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD	Υ	Υ	38T76AA
	Z Turbo 1TB 2280 PCIe-4x4 TLC SSD	Υ	Υ	38T77AA
	Z Turbo 1TB 2280 PCIe-4x4 TLC Z8 Kit SSD	N	Υ	360H5AA
	Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z8 Kit SSD	N	Υ	360H4AA
	Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD	Υ	Υ	38T79AA
	Z Turbo 2TB 2280 PCIe-4x4 TLC SSD	Υ	Υ	38T75AA
	Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z8 Kit SSD	N	Υ	360H1AA
	Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD ²	Υ	Υ	5S496AA/AT
	Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD ²	Υ	Υ	5S497AA/AT



Supported Components

Z Turbo 4TB 2280 PCIe-4x4 SED 0PAL2 TLC M.2 Z8 Kit SSD ²	N	Υ	5S4A0AA
HP Z Turbo Drive Dual Pro			
HP Z Turbo Drive Dual Pro PCIe-4x4 NVMe Carrier ¹	Υ	Υ	56Q86AA
HP Z Turbo Drive Dual Pro 512GB TLC SSD	Υ	N	
HP Z Turbo Drive Dual Pro 1TB TLC SSD	Υ	N	
HP Z Turbo Drive Dual Pro 2TB TLC SSD	Υ	N	
HP Z Turbo Drive Dual Pro 4TB TLC SSD ²	Υ	N	
Intel® Virtual RAID on CPU (Intel® VROC) for NVMe			
Intel VROC NVMe SSD Premium Ctlr Module ²	N	Υ	3FJ81AA
Intel VROC NVMe SSD Standard Ctlr Module ³	N	Υ	3FJ80AA

Note 1: Kit includes dual pro carrier and heatsink. Requires separate purchase of Z Turbo PCIe 4x4 M.2 SSD modules.

Note 2: Enables RAID 0, 1 & 10

Note 3: Enables RAID 0, 1 & 10 plus RAID 5 with write hole closure options

Note 4: Available in June 2023

NOTE: Internal M.2 PCIe SSDs are installed using HP Personality Card (up to 2 Personality Cards per system). Each Personality Card can support two M.2 drives.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
Graphics Cable	HP DisplayPort To VGA Adapter	N	Υ	AS615AA/AT	
Adapters	HP DisplayPort To VGA Adapter	N	Υ	F7W97AA	
	HP DisplayPort to HDMI Adapter	Υ	Υ	2JA63AA	
	HP (Bulk 12) miniDP-to-DP Adapter Cables	N	Υ	2KW87A6	
	HP Single miniDP-to-DP Adapter Cable	Υ	Υ	2MY05AA	
	HP miniDP-to-DP Adapter (2-pack)	Υ	N		
	HP miniDP-to-DP Adapter (4-pack)	Υ	N		
	HP miniDP-to-DP Adapter (8-pack)	Υ	N		
	HP DisplayPort To DVI Adapter (Bulk 90)	N	Υ	FH973A6	
	NVIDIA NVLink 3-Slot Bridge	Υ	Υ	340L3AA	
	NVIDIA 3D Stereo Bracket	N	Υ	K0A25AA	
Ultra High-End	NVIDIA® RTX 6000 Ada 48GB1	Υ	Υ	79C23AA/AT	3
Graphics	NVIDIA® RTX A6000 48GB	Υ	Υ	2S6U3AA/AT	2
	AMD Radeon Pro W6800 32 GB ²	Υ	Υ	340K7AA	2
	NVIDIA® RTX A5000 24GB	Υ	Υ	20X23AA/AT	2
	NVIDIA® Quadro® Sync II	N	Υ	1WT20AA	
High-End Graphic	s NVIDIA® RTX A4500 20GB1	Υ	Υ	5S458AA/AT	2
	NVIDIA® RTX A4000 16GB	Υ	Υ	20X24AA/AT	2
	NVIDIA® Long-Life RTX A4000E 16GB ¹	Υ	Υ	6H7J7AA/AT	2
Midrange Graphics	NVIDIA® RTX A2000 12GB	Y	Υ	5Z7D9AA/AT	2



Supported Components

	NVIDIA® Long-Life RTX A2000E 12GB	Υ	N		2
	NVIDIA® T1000 8GB	Υ	Υ	5Z7D8AA/AT	2
	NVIDIA® Long-Life T1000E 8GB	Υ	Υ	6V9V4AA/AT	2
	AMD® Radeon™ Pro W6600 8GB²	Υ	Υ	340K5AA	2
Entry Graphics	NVIDIA® T400 4GB	Υ	Υ	5Z7EOAA/AT	2
	AMD® Radeon™ RX 6400 4GB²	Υ	Υ	6Q3U4AA/AT	1
	NVIDIA T1000 4 GB	Υ	Υ	20X22AA/AT	2
	Intel Arc Pro A40 6GB ¹	Υ	Υ	6E3Y8AA	1

Note 1: available in July 2023

Note 2: 2nd AMD graphic card configurable in July 2023

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	32GB (2x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	64GB (4x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1
	64GB (2x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	128GB (8x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1
	128GB (4x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1
	256GB (16x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		2
	256GB (8x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1
	256GB (4x64GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1
	512GB (16x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		2
	512GB (8x64GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1
	1TB (16x64GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		2
	After Market Options				
	16GB (1x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	Υ	340K1AA	
	32GB DDR5 (1x32GB) 4800 DIMM ECC REG Memory	N	Υ	340K2AA	
	64GB DDR5 (1x64GB) 4800 DIMM ECC REG Memory	N	Υ	340K3AA	

Note 1: Memory configuration is available for both single and dual CPU configurations.

Note 2: Memory configuration is only available with dual CPU configuration.

Multimedia and Audio Devices		Factory Configured	Option Kit	Option Kit Part Number
	HyperX Cloud Mix Wireless Gaming Headset	N	Υ	4P5K9AA
	HyperX Cloud Core Gaming Headset	N	Υ	4P4F2AA
	HyperX Cloud Flight Wireless Gaming Headset	N	Υ	4P5L4AA
	HyperX Cloud Stinger Core Gaming Headset	N	Υ	4P4F4AA
	HyperX SoloCast - USB Microphone	N	Υ	4P5P8AA
	Integrated Realtek ALC 3205-CG	Υ	N	



Supported Components

Optical and
Removable
Storage

	Factory Configured	Option Kit	Option Kit Part Number
HP CRU QX428 Removable with 415mm Cable Frame/Carrier ^{1,4}	Υ	Υ	5B0U7AA
HP DX175 Removable HDD Frame/Carrier ^{2,4}	Υ	Υ	1ZX71AA
HP DX175 Removable HDD Spare Carrier ^{2,4}	N	Υ	1ZX72AA
HP CRU Secure High Performance Storage Module with 2TB M.2 SSD ³	Υ	Υ	56Q87AA
HP CRU Secure High Performance Storage Module with 1TB M.2 SSD ³	Υ	Υ	56Q88AA
HP CRU Secure High Performance Storage Module with 512GB M.2 SSD ³	Y	Υ	56Q89AA
HP 9.5mm Slim DVD-ROM Drive	Υ	Υ	K3R63AA
HP 9.5mm Slim BDXL Blu-Ray Writer Drive	Υ	Υ	K3R65AA
HP 9.5mm Slim SuperMulti DVD Writer	Υ	Υ	K3R64AA

Note 1: Requires separate purchase of HP CRU Secure High Performance Storage (SHIPS) Module(s).

Note 2: Only supports 4TB or lower capacity HDDs.

Note 3: Kit contains CRU Secure High Performance Storage (SHIPS) Module and M.2 SSD for install into a factory configured or after market option front removeable storage carrier (HP CRU QX428 Frame/Carrier).

Note 4: Planned to be available in June 2023

Networking and Communications

	Factory Configured	Option Kit	Option Kit Part Number
HP Dual Port 10GbE NIC G2	Υ	Υ	360K6AA
Intel® X550 10GBASE-T Dual Port NIC	Υ	Υ	1QL46AA
Intel® I225-T1 Single Port 2.5GbE PCIe NIC	Υ	Υ	406L9AA
Intel® Ethernet I350-T4 4-Port 1Gb NIC	N	Υ	W8X25AA
Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC	Υ	Υ	1C7Q2AA
Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Υ	Υ	6E3Y9AA/AT
NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC	Υ	Υ	436M8AA
Intel AX210 Wi-Fi 6E non-vPro + Bluetooth® 5.2 with External Antenna WLAN	Υ	Υ	340L7AA

Note1: 3rd party transceivers sold separately. You must have a transceiver installed to connect this card to a network.

Racking and	
Physical Security	Į

	Factory		Option Kit
	Configured	Option Kit	Part Number
HP Z640/Z840/Z8 G4 Rail Rack Kit	N	Υ	2FZ77AA/AT
HP Z8 Rack Rail Upgrade Kit	N	Υ	2FZ76AA/AT

Input Devices

	Factory Configured	Option Kit	Option Kit Part Number
HP 320K Wired Keyboard	Υ	Υ	9SR37AA/ET/UT
HP 125 Wired Keyboard	Υ	Υ	266C9AA/ET/UT
HP 975 USB+BT Dual-Mode Wireless Keyboard	N	Υ	3Z726AA/ET/UT
HP 455 Programmable Wireless Keyboard	N	Υ	4R177AA/ET/UT/A6
HP Wired Desktop 320MK Mouse and Keyboard	N	Υ	9SR36AA/ET/UT



Supported Components

HP 655 Wireless Keyboard and Mouse Combo	N	Υ	4R009AA/ET/UT/A6
HP Wired 320M Mouse	Υ	Υ	9VA80AA/ET/UT
HP Creator 935 Black Wireless Mouse	N	Υ	1D0K8AA/ET/UT
HP 128 LSR Wired Mouse	Υ	Υ	265D9AA/ET/UT
HP 125 Wired Mouse	N	Υ	265A9AA/ET/UT
HP Business Slim Smartcard Keyboard	Υ	Υ	Z9H48AA/AT

NOTE: Keyboard and Mouse are optional or add on features.

Other Hardware		Factory Configured	Option Kit	Option Kit Part Number
	HP C13 1.83m Power Cord Kit (halogen-free)	Υ	N	
	HP Z8 1450W C19 2.5m Power Cord Kit ^{3,**}	N	Υ	6Z9V1AA
	HP 2.5in to 3.5in HDD Adapter Kit	N	Υ	J5T63AA/A6
	HP Internal Serial+PS/2 Port	Υ	Υ	56Q78AA
	HP Dual TBT4 PCIe x4 Low Profile Card⁵	Υ	Υ	340L1AA
	HP USB 2.0 Type-A Port Adapter Kit ⁴	Υ	Υ	79C24AA
	HP 2.5in HDD/SSD 2-in-1 Optical Bay Bracket	N	Υ	K4T74AA
	HP Optical Bay HDD Mounting Bracket ¹	N	Υ	NQ099AA
	HP SD 4 Card Reader Zx G4	Υ	Υ	2VK54AA
	HP C13 1.83m Power Cord Kit ^{2,*}	N	Υ	6Z1T9AA

^{*}Does not support HP Z8 G5 1450W PSU.

Note 1: NQ099AA HP Optical Bay HDD Mounting Bracket is required as a separate purchase for HDD option kits installed into an external bay.

Note 2: 6Z1T9AA is only for 1125W PSU Z8 G5. **Note 3:** 6Z9V1AA is only for 1450W PSU Z8 G5.

Note 4: The USB 2.0 Type-A Port Adapter Kit has a single USB 2.0 type A connector.

Note 5: Available in July 2023

Software		Factory Configured	Option Kit	Support Notes
	HP Anyware	Υ	N	
	HP Performance Advisor	Υ	N	1
	HP PC Hardware Diagnostics UEFI (Windows OS only)	Υ	N	2
	HP PC Hardware Diagnostics Windows	Υ	N	
	HP Wolf Security	Υ	N	3
	HP Notifications	Υ	N	
	HP Desktop Support Utility	Υ	N	
	HP Documentation	Υ	N	
	myHP	Υ	N	
	HP Easy Clean	Υ	N	
	Kingsoft WPS Office	Υ	N	4
	Z by HP Data Science Stack Manager	Υ	N	5, 6
	WSL2/Ubuntu Data Science Stack	Υ	N	5



^{**}Does not support HP Z8 G5 1125W PSU.

Supported Components

HP Image Assistant N N N HP Support Assistant N N N HP Smart Health N N N

Note 1: Supported with Windows only. Also available as a free download from

http://www.hp.com/go/performanceadvisor

Note 2: Windows OS only Note 3: Not available in Russia Note 4: Not available in China

Note 5: Only available with NVIDIA® graphics

Note 6: Only available with Ubuntu

Operating Systems Windows 11 Pro for Workstations^{1,2}

Windows 11 Pro for Workstations (preinstalled with Windows 10 Pro for Workstations Downgrade)^{1,2,3}
Ubuntu 22.04 LTS⁴
HP Linux®-ready

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282



¹ Windows Enterprise sold separately and requires that customer have an enterprise license from Microsoft.

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

Supported Components

HP BIOS

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate
 the HP Z8 G5 Workstation into the enterprise, such as PXE, remote recovery, remote
 configuration, remote control, and BIOS (F10) Setup support for 15 languages.
- Network firmware updates —Update your BIOS via the cloud or standardize on a BIOS version hosted on an Enterprise network.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Class 3 UEFI specification version 2.7
- Absolute Persistence agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Workstation computer in any enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Workstation computers, including BIOS updates from within Windows (HP Firmware Update and Recovery), Capsule update, HP Client Manager, and fail-safe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides the same capability within BIOS (F10) Setup. The BIOS Configuration Utility is available from the HP support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery. Additional HP BIOS Features:
 - Power-On password Helps prevent an unauthorized user from powering on the system.
 - Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
 - S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - Power to expansion connectors / slots
 - Most Wake events other than power buttons and WOL (Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
 - USB charging ports

HP Sure Start Gen7

- BIOS Integrity checking Sure Start protection ensures that only trusted BIOS code is
 executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown
 and while the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is
 policy driven for better manageability. Start is set by default to automatically repair the BIOS
 if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.
- Audit enabled System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating.



Supported Components

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

HP BIOSphere Gen613 **HP DriveLock & Automatic DriveLock** BIOS Update via Network Master Boot Record Security Power On Authentication Absolute Persistence Module²³ **Pre-boot Authentication HP Wireless Wakeup**

Software

HP Desktop Support Utility HP Performance Advisor¹ **HP Privacy Settings HP Notifications** myHP

Manageability Features

HP Driver Packs² HP System Software Manager (SSM) **HP BIOS Config Utility (BCU) HP Client Catalog** HP Manageability Integration Kit Gen6³

Client Security Software

HP Wolf Security (Including HP Sure Click & HP Sure Sense)²² HP Pro Wolf Security (Including Credential Manager)¹⁸ HP Client Security Manager Gen 74 HP Sure Run9 HP Sure Recover¹⁰ **HP Power On Authentication** Microsoft Defender⁷

Security Management

HP Security Update Service (SUS) Secure Erase¹⁶ TPM 2.0 Embedded Security Chip(Common Criteria EAL4+ Certified)²⁴ SATA port disablement (viaBIOS) Serial, USB enable/disable (viaBIOS) Power-on password (viaBIOS) Setup password (viaBIOS) Support for chassis padlocks and cable lock devices Integrated hood sensor0 HP Sure Start Gen48

⁴ HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.



¹ HP Performance Advisor Software - HP Performance Advisor is ready to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: http://hp.com/PerformanceAdvisor

² HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

³ HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html

Supported Components

- ⁷ Microsoft Defender Opt in and internet connection required for updates.
- ⁸ HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.
- ⁹ HP Sure Run Gen5 is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors
- ¹⁰ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module
- ¹³ HP BIOSphere Gen6 features may vary depending on the platform and configurations.
- ¹⁶ Secure Erase For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane.
- ¹⁸ HP Wolf Pro Security Edition is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.
- ²² HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features
- ²³ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- ²⁴ Firmware TPM is version 15.21. Hardware TPM is v2.0.



System Technical Specifications

System Board

System Board Form

Approximately 415.04mm x 386.08mm (16.34 x 15.20 inches)

Factor

Dual LGA-4677 **Processor Socket CPU Bus Speed** DMI Gen3 x 8 lanes.

3 UPI x24 interconnects between CPUs that operate at 16GT/s

Chipset Intel C741 Emmitsburg PCH

Super I/O Controller Nuvoton SIO21

Memory Expansion Slots 16 DDR5 memory slots (only 8 DDR5 memory slots with single CPU installed)

Memory Type Supported DDR5, RDIMM (Registered) ECC

Memory Modes Non-Interleaved for single channel. Interleaved when multiple channels are populated **Memory Speed Supported** Max memory speed is processor-dependent, refer to processor table for more details:

4800MT/s DDR5 or 4400MT/s DDR5 or 4000MT/s DDR5

Memory Protection ECC Maximum Memory 1TB

Memory Configuration

16GB, 32GB and 64GB RDIMMs are supported.

(Supported)

64GB RDIMMs cannot be mixed with other module capacities in the same system.

NVDIMM Memory No

PCI Express Connectors

CPUO Standard PCIe Slots:

• 1 PCI Express Gen5 slot x16 mechanical/ x16 electrical (full height, full length) • 1 PCI Express Gen4 slot x16 mechanical/x16 electrical (full height, full length) • 1 PCI Express Gen3 slot x8 mechanical/ x8 electrical (full height, full length) • 1 PCI Express Gen3 slot x4 mechanical/x4 electrical (full height, full length)

CPUO Personality Slots:

 1 PCI Express Gen4 slot x8 mechanical/x8 electrical (full height, half length) (supports two x4 M.2 devices per personality slot)

CPUO Other PCIe Connections

- 1 Front NVMe Storage SlimSAS PCIe Gen4 x8 (supports two x4 M.2 devices via QX428)
- 1 10GbE (PCIe Gen3 x4)

CPU 1 Standard PCIe Slots:

 1 PCI Express Gen4 slot x16 mechanical/ x16 electrical (full height, full length) • 1 PCI Express Gen3 slot x16 mechanical/x16 electrical (full height, full length)

CPU1 Personality Slots:

 1 PCI Express Gen4 slot x8 mechanical/x8 electrical (full height, half length) (supports two x4 M.2 devices per personality slot)

PCH Standard PCIe Slots:

• 1 PCI Express Gen3 slot x4 mechanical/x4 electrical (full height, full length)

Supported Drive Interfaces

SATA Number of SATA ports: 6

Intel® SATA controller: secondary SATA

On-board RAID Support Integrated RAID

Intel® VROC® SATA RAID 0, 1, 5, and 10 supported on Windows 10 and

11, RHEL 8.6 and later, SLE 15 SP4 and later

Intel® VROC® NVMe RAID 0, 1, 5, and 10 supported with presence of appropriate VROC upgrade module (after-market kits) on Windows 10

and 11, RHEL 8.6 and later, SLE 15 SP4 and later



System Technical Specifications

Factory Configured RAID: None

Integrated Graphics No

Network Controller Intel WGI210AT and WGI219LM.

WGI219LM LOM provides Management capabilities: WOL, PXE 2.1,

DASH 1.1 and AMT

External SATA (eSATA) No

Serial 1 internal header (requires optional Serial Port Adapter Kit)

2nd Serial No **HD Integrated Audio** Yes

USB Connector(s) Front Front I/O:

4x USB 3.1 Gen1 Type-A (left-most port supports Battery Charging

1.2

Charging USB Type-A port provides 1.5 Amps @ 5 Volts
Standard USB Type-A Ports provide 900mA @ 5 Volts

Rear 6x USB 3.1 Gen1 Type-A via USB hub.

Internal 1 USB 3.1 Gen1 (via USB hub) header, with a single 12-pin shrouded

connector. This header supports a USB Media Card reader.

1 USB 2.0 single port header 1 USB 2.0 dual port header

HD Integrated Audio Yes Flash ROM Yes

CPU Fan Header Yes (CPU0 and CPU1)

Memory Fan Header No Chassis Fan Header Yes (2)

Front PCI Fan Header Via Aux fan header if needed.

Front Control

Panel/Speaker Header

CMOS Battery Holder - Y

Lithium

Yes

Integrated Trusted Platform Module

Integrated TPM 2.0.

Platform Module Convertible to FIPS 140-2 Certified Mode through firmware v15.21.

The TPM module is disabled where restricted by law.

Power Supply Headers Yes
Power Switch, Power LED Yes
& Hard Drive LED Header
Clear Password Jumper Yes

Keyboard/Mouse USB and PS/2 (option)

¹Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 11 Professional 64 bit, Red Hat Linux 64-bit.

²M.2 storage supports compatible devices up to 80mm

System Technical Specifications

System Configuratio		1	•					
Example Configuration	Processor Info		n® 5415+ 8C 2.					
#1	Memory Info	32GB DDR5 (2	2x16GB) RegRA	M.				
	Graphics Info	1x NVIDIA® A	1x NVIDIA® A2000					
	Disks/Optical/Floppy	1x 1TB Intern	al SATA HDD +	1x DVDRW SA	TA			
	PSU	1125W						
	Other	N/A						
Energy Consumption		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	97.	783	93.	632	96.	522	
	Windows Busy Typ (S0)	255	.653	253	3.33	252	2.18	
	Windows Busy Max (S0)	258	.699	253	.884	253	.224	
	Sleep (S3)	4.266	4.178	4.246	4.189	4.218	4.176	
	Off (S5)	1.689	1.681	1.699	1.697	1.654	1.631	
	Zero Power Mode (EuP)	0.2	221	0.3	323	0.2	219	
	1					1		
Heat Dissipation		115	VAC	230 VAC		100 VAC		
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	333	.635	319	.472	329	.333	
	Windows Busy Typ (S0)	872.288		864.362		860.438		
	Windows Busy Max (S0)	882.681		866.252		864.000		
	Sleep (S3)	14.556	14.255	14.487	14.293	14.392	14.249	
	Off (S5)	5.763	5.736	5.797	5.790	5.643	5.565	
	Zero Power Mode (EuP)	0.7	754	1.102		0.747		
Example Configuration	Processor Info	2x Intel® Xeo	n® 5415+ 8C 2.	9GHz 150W				
#2	Memory Info	64GB DDR5 (4	1x16GB) RegR <i>l</i>	λM				
	Graphics Info	1x NVIDIA® A	4000					
	Disks/Optical/Floppy	2x 1TB SATA	HDD + 2x 4TB I	nternal M.2 SS	D + 1x DVDRW	SATA		
	PSU	1125W						
	Other	N/A						
Energy Consumption		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	167	.365	158	.346	166	5.35	
	Windows Busy Typ (SO)	474	.655	472	.688	471	.555	
	Windows Busy Max (S0)	508	.788	506	.355	506	.141	
	Sleep (S3)	5.785	5.682	5.564	5.488	5.543	5.418	
	Off (S5)	2.217	2.117	2.237	2.268	2.208	2.104	
	Zero Power Mode (EuP)		246		351	1	238	
		115	VAC	230	VAC	100	VAC	
	1	1		I.		1		



System Technical Specifications

		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	571.049		540	.277	567.586		
Heat Dissipation	Windows Busy Typ (S0)	1619).523	1612	2.811	1608	3.946	
(Btu/hr)	Windows Busy Max (S0)	1735	5.985	1727	'.683	1726.953		
	Sleep (S3)	19.738	19.387	18.984	18.725	18.913	18.486	
	Off (S5)	7.564	7.223	7.633	7.738	7.534	7.179	
	Zero Power Mode (EuP)	0.839 1.197			97	0.812		
Example Configuration	Processor Info	2x Intel® Xeor	n® 6426Y 2.6G	Hz 16C 185W				
#3	Memory Info	256GB DDR5 (16x16GB) RegRAM						
	Graphics Info	1x NVIDIA® A6	5000					
	Disks/Optical/Floppy	4x 4TB Intern	al M.2 SSD + 1	OVDRW SATA				
	PSU	1450W						
	Other	N/A						

Energy Consumption		115 VAC		230 VAC		100 VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	200.685		196.652		198.568	
	Windows Busy Typ (S0)	627.685		625.992		625.147	
	Windows Busy Max (S0)	658.742		654.668		653.472	
	Sleep (S3)	7.689	7.599	7.674	7.569	7.673	7.558
	Off (S5)	2.425	2.418	2.498	2.459	2.368	2.407
	Zero Power Mode (EuP)	0.2	0.278		169	0.269	

Heat Dissipation	ion 115 VAC		VAC	230	VAC	100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	684.737		670.977		677.514	
	Windows Busy Typ (S0)	2141.661		2135.885		2133.002	
	Windows Busy Max (S0)	2247.628		2233.727		2229.646	
	Sleep (S3)	26.235	25.928	26.184	25.825	26.180	25.788
	Off (S5)	8.274	8.250	8.523	8.390	8.080	8.213
	Zero Power Mode (EuP)	0.9	949	1.682		0.918	

Example Configuration	Processor Info	2x Intel® Xeon® 6430 32C 1.9GHz 270W				
#4	Memory Info	1024GB DDR5 (16x64GB) RegRAM				
	Graphics Info	2x NVIDIA® A6000				
	Disks/Optical/Floppy	4x 4TB Internal M.2 SSD + 1x DVDRW SATA				
	PSU	1450W				
	Other	N/A				

Energy Consumption		115	115 VAC		230 VAC		100 VAC	
(Watts)		LAN Enabled LAN Disabled		LAN Enabled LAN Disabled		LAN Enabled LAN Disabled		
	Windows Idle (S0)	238	.334	216	.387	236	.884	



System Technical Specifications

Windows Busy Typ (S0)	830.883		827.664		826.456	
Windows Busy Max (S0)	977.655		974.	662	973.	481
Sleep (S3)	18.864	18.175	18.688	18.162	18.674	18.115
Off (S5)	2.738	2.718	2.748	2.729	2.721	2.705
Zero Power Mode (EuP)	0.2	297	0.4	38	0.2	96

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	813.	.196	738	.312	808	.248
	Windows Busy Typ (S0)	2834	1.973	2823	3.990	2819	.868
	Windows Busy Max (S0)	3335.759		3325.547		3321.517	
	Sleep (S3)	64.357	62.013	63.763	61.969	63.716	61.808
	Off (S5)	9.342	9.274	9.376	9.311	9.284	9.229
	Zero Power Mode (EuP)	1.0	113	1.7	'34	1.0	10

NOTE: The numbers in this table are from actual measurements on a single system. There will be some variation from unit to unit.

NOTE: The busy power number and associated BTU/hr number for each configuration will be a strong function of the actual application software run on the system. There can be a great deal of variation in this number.

NOTE: The Power Supply Efficiency report may be found at the following links: https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2



System Technical Specifications

Operating Voltage Range90-269 VACRated Voltage Range100-240 VACRated Line Frequency50-60 HzOperating Line Frequency47-66 Hz

Range

ENERGY STAR® certified Yes

(Config Dependent)

CECP Compliant @ 220V Yes

FEMP Standby Power

er Yes, with Wake-on-LAN disabled: <1W in S5 - Power Off

Compliant

Built-in Self Test (BIST) Yes

LED

Surge Tolerant Full Yes **Ranging Power Supply** (withstands power surges

up to 2000V)

Hood Lock Header Yes
ErP Lot 6- Tier 1 Yes
Compliance @ 230V (<1W

in S5 - Power Off)

ErP Lot 6- Tier 2 Yes Compliance @ 230V

(<0.5W in S5 - Power Off)

System Configuration (Entry level)	Processor Info	1 x Intel Sapphire Rapids 16C 150W		
	Memory Info	2 x 16GB DDR5-4800 RDIMM		
	Graphics Info	1 x NVIDIA RTX A2000		
	Disks/Optical	1 x 1TB HDD / Blu-Ray R/RE DVD+/-RW		
	Power Supply	1125W		
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)	
	Idle	3.8	19	
	Hard drive Operating (Drive Random Seek)	3.9	20	
	Active Mode	3.8	19	
System Configuration	Processor Info	2 x Intel Sapphire Rapids 16C 150W		
(Mid-level)	Memory Info	4 x 16GB DDR5-4800 RDIMM		
	Graphics Info	1 x NVIDIA RTX A4000		
	Disks/Optical	2 x 512GB M.2 + 2 x 1TB HDD / Blu-Ray DVD+/-RW		
	Power Supply	1125W		
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)	
	Idle	3.7	19	
	Hard drive Operating (Drive Random Seek)	3.8	21	



System Technical Specifications

	Active Mode	3.8	20	
System Configuration	Processor Info	2 x Sapphire Rapids 32C 270W		
(High-end)	Memory Info	16 x 64 GB DDR5-4800 RDIMM		
	Graphics Info	2 x NVIDIA RTX A6000		
	Disks/Optical	4 x 4TB M.2 + 4 x 8TB HDD / Blu-Ray DVD+/-RW		
	Power Supply	1450W		
Declared Noise Emission		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)	
	Idle	4.0	24	
	Hard drive Operating (Drive Random Seek)	4.2	24	
	Active Mode	4.1	24	

Environmental Requirements

Temperature Operating: 5° to 40°C (40° to 104°F)¹

Non-operating: -40° to 60°C (-40° to 140°F)

¹40°C has been validated for configs up to 2x 270W CPU (Intel Xeon Gold 6430), 2x NVIDIA® RTX A4000 graphics cards, 8x64GB RAM, 4x 2TB M.2

storage, 2x 2TB HDD storage, and 1125W PSU

Humidity Operating: 8% to 85% RH, non-condensing

Non-operating: 8% to 90% RH, non-condensing

Maximum Altitude Operating: 3,048 m (10,000 feet)

Non-operating: 9,144 m (30,000 feet)

Dynamic Shock

Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20g

NOTE: Values represent individual shock events and do not indicate

repetitive shock events

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g 2 /Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g 2 /Hz

NOTE: Values do not indicate continuous vibration.

Cooling Above 1524 m (5,000 feet) altitude, the maximum operating temperature

is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation,

up to 3048 m (10,000 feet)

System Technical Specifications

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information

Optical Drive Tool-less, 2nd Optical Drive requires a 5.25" bay carrier

Hard Drives Tool-less **Expansion Cards** Tool-less

Processor Socket Screw-in processor coolers

Blue User Touch Points Yes, on tool-less internal chassis mechanisms

Color-coordinated Cables Yes

and Connectors

Memory Tool-less

System Board Tool-less, retained by Front Card Guide and Top Memory Fan Holder

Power and HD LED on

Yes **Front of Computer**

Configuration Record SW Yes **Over-Temp Warning on**

Yes

Dual Function Front

Power Switch

Screen

Yes, causes a fail-safe power off when held for 4 seconds

Padlock Support No

Cable Lock Support Yes, Kensington Cable Lock (optional): Prevents entire system theft only. 3mm x 7mm slot at rear of

system

No

Universal Chassis Clamp

Lock Support

Solenoid Lock and Hood No

Sensor

Rear Port Control Cover No Serial, USB, Audio, Yes Network, Enable/Disable

Port Control

Removable Media Yes

Write/Boot Control

Power-On Password Yes

Setup Password Yes, prevents an unauthorized person from changing the workstation configuration.

3.3V Aux Power LED on

System PCA

None

NIC LEDs (integrated)

(Green & Amber)

Yes

CPUs and Heatsinks A torx driver (T30) is needed to remove the processor heatsink. CPU attached to heatsink via tool-less

clip

Power Supply Diagnostic Yes

LED

Front Power Button

Front Power LED Yes, white (normal), red (fault)

Front Hard Drive Activity Yes, white

LED

Front ODD Activity LED Yes **Internal Speaker** Yes



System/Emergency ROM Yes

Flash Recovery

Air cooled forced convection **Cooling Solutions Power Supply Fans** 2x - Dual Side Inlet Blowers

CPU Heatsink Fan 92 mm x 92 mm x 25.4 mm for each CPU

Chassis Fan Rear: 120 mm x 38 mm

Front Lower: 120 mm x 25.4 mm (PCle zone)

Memory Heatsink Fan Front Upper: 92mm x 25mm (upper memory bank);

Front Middle: 80mm x 25mm (lower memory bank)

HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on **HP PC Hardware Diagnostics UEFI**

many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a

download from HP Support.

Access Panel Key Lock Yes, left access panel

ACPI-Ready Hardware Advanced Configuration and Power Management Interface (ACPI).

Allows the system to wake from a low power mode.

Controls system power consumption, making it possible to place individual cards and peripherals in a

low-power or powered-off state without affecting other elements of the system.

Integrated Chassis

Handles

Yes, front and rear

Power Supply Tool-less, rear access direct-connect (blind-mate)

PCI Card Retention Yes, rear (all), middle (full-height cards), front (cards with extender)

Flash ROM Yes **Diagnostic Power Switch** Yes

LED on board

Clear Password Jumper Yes **Clear CMOS Button** Yes **CMOS Battery Holder** Yes **DIMM Connectors** Yes

Service, Support, and Warranty

On-site Warranty and Service¹: One-year, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - 5pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering, 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise class HDDs.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider. and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at:

http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Certification and Compliance

Environmental Sustainability questions concerning:

Ecolabels (EPEAT, TCO, etc.)



- ENERGY STAR. California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uken/certifications/technical/regulations-certificates.html?jumpid=ex r135 uk/en/any/corp/hpukmu chev/certificates)
- **GS** Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- **CCC Certificates**
- **Ergonomics**

Please contact techregshelp@hp.com

BIOS

Full BIOS support for PCI Express through industry standard interfaces. Supported speeds and slot PCIe 5.0 Support

information vary.

AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b ATA/ATAPI

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is WMI Support

fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

Users can define a specific date and time for the system to power on. **BIOS Power On**

ROM Based Computer Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM

Flash Recovery with

Video

Recovers system BIOS in corrupted Flash ROM.

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). **Replicated Setup**

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup). System Management BIOS Reference Specification, Version 3.2

Disables the ability to boot from removable media on supported devices. **Boot Control**

Memory Change Alert

SMBIOS

Alerts management console if memory is removed or changed. Thermal Alert Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

 ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash Provides secure, fail-safe ROM image management from a central network console.

Allows the system to enter and resume from low power modes (sleep states). ACPI (Advanced

Configuration and Power Enables an operating system to control system power consumption based on the dynamic workload. Management Interface) Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 6.0 for full compatibility with 64-bit operating systems.

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen. Ownership Tag

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Shutdown

Instantly Available PC (Suspend to RAM - ACPI Allows for very low power consumption with quick resume time.

sleep state S3)

Remote System Installation via F12 (PXE operating system. 2.1) (Remote Boot from

Allows a new or existing system to boot over the network and download software, including the

Server)

ROM revision levels Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is

available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

level Start-up Diagnostics Revision level is digitally encoded into the HW and cannot be modified. Assesses system health at boot time with selectable levels of testing.

Allows management SW to read revision level of the system board.

(Power-on Self-Test) Auto Setup when new

hardware installed

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Localized ROM Setup Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with

local keyboard mappings.

Asset Tag The user or MIS to set a unique tag string in non-volatile memory.

Allows I/O slot parameters (option ROM enable/disable, bifurcation, speed) to be configured Per-slot Control

individually.

2.7

Adaptive Cooling

Control parameters are set according to detected hardware configuration for optimal acoustics.

Pre-boot Diagnostics

(Pre-video) critical errors are reported via beeps and blinks on the power LED.

UEFI Specification

Revision

ACPI

Advanced Configuration and Power Management Interface, Version 6.0

CD Boot "El Torito" Bootable CD-ROM Format Specification Version 1.0

EHCI Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0

PCI Express PCI Express Base Specification, Revision 2.0

> PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0 PCI Express Base Specification, Revision 5.0

Serial ATA Specification, Revision 1.0a **SATA**

> Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD JEDEC JESD300-5

TPM Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9672).

Common Criteria EAL4+ certified.

FIPS 140-2 Certification

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

> Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 Specification Universal Serial Bus Revision 3.2 Specification USB Battery Charging specification, Revision 1.2 USB Power Delivery specification Revision 3.0

SMBIOS System Management BIOS Reference Specification, Version 3.2

System Technical Specifications

Social and Environmental Responsibility

& Declarations

Eco-Label Certifications This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- ENERGY STAR® (energy-saving features available on selected configurations-Windows
- US Federal Energy Management Program (FEMP)
- EPEAT[®] Gold registered worldwide
- TCO Certified
- China Energy Conservation Program (CECP)

Sustainable Impact **Specifications**

- Ocean-bound plastic in system fans
- 40% post-consumer recycled plastic
- Contains 10% post-industrial recycled metal
- Internal Power Supply 90% efficient

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data is based on a "Typically Configured Desktop Workstation".

Energy Consumption (in accordance with US

ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz
Normal Operation (Sort idle)	135.86W	135.88W
Normal Operation (Long idle)	126.10W	126.19W
Sleep	8.35W	8.36W
Off	2.11W	2.11W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz
Normal Operation (Short idle)	463.28 BTU/hr	463.35 BTU/hr
Normal Operation (Long idle)	430.00 BTU/hr	430.31 BTU/hr
Sleep	28.47 BTU/hr	28.51 BTU/hr
Off	7.20 BTU/hr	7.20 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions

(in accordance with	Sound Power	Sound Pressure
ISO 7779 and ISO 9296)	(L _{WAd} , bels)	(L _{pAm} , decibels)
Typically Configured – Idle	3.7	19
Drive Random Seek	3.8	21
Active Mode	3.8	20



Longevity and **Upgrading**

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- 3 USB ports
- 1 PC card slot (type I/II)
- 1 ExpressCard/54 slot
- 1 IEEE 1394 Port
- 2 SODIMM memory slots
- Optional expansion base docking station
- 1 multi-bay II storage port
- Interchangeable HDD

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery in this product complies with EU Directive 2006/66/EC

Battery size: CR2032 (coin cell) Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40 ppm by weight

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and IS01043.
- This product is 94.8% recycle-able when properly disposed of at end of life.

Packaging Materials

Internal:

External: PAPER/Corrugated At least 35% Recycled

> PAPER/Molded Pulp 100% Recycled PLASTIC/Polyethylene low 80% Recycled

density - LDPE

The corrugated paper packaging materials contains at least 62.5% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these quidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.



The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

footnotes

- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.

Manageability

Industry Standard Specifications Intel® Active Management Technology (AMT)

This product meets the following industry standard specifications for manageability functionality:

DASH 1.1 (via Intel[®] LAN on motherboard)

Intel® Active Management Intel® Active Management Technology (AMT) 15.20

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 15.20 includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
 - o Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- Agent Presence
- System Defense Filters
- Serial Over LAN (SOL)
- USB Redirect (Media Redirection)
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.2 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements



System Technical Specifications

- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC
- Remote Memory Dump Command Creates memory dump for debug

Intel® vPro™ Technology

Yes, when configured with an Intel® vPro™ supporting processor.



Technical Specifications - Stable & Consistent Offerings

Stable & Consistent Offerings

Global Series SKUs

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware and software designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

Stable & Consistent Offerings

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware and software components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

Processors	Product #	Offering
	3F4D7AV	Intel Xeon 5415+
	3F4D3AV	Intel Xeon 4410Y
Graphics	Product #	Offering
	6Z325AV	NVIDIA Long-Life T1000E
	6Z319AV	NVIDIA Long-Life RTX A2000E
	6Z321AV	NVIDIA Long-Life RTX A4000E
	6B4J4AV	AMD Radeon RX 6400
	3F2W5AV	AMD Radeon Pro 6600
Storage	Product #	Offering
	3F3A6AV	Z Turbo 1TB PCIe-4x4 2280 TLC M.2 Solid State Drive
	3F4E6AV	1TB 7200RPM SATA 3.5in Enterprise



Technical Specifications - Hard Drives

STORAGE/HARD DRIVES

Performance PCIe SSDs for HP Workstations

Z Turbo 512GB 2280 PCIe-4x4 TLC SSD Capacity 512GB
Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6400MB/s*

Nο

Sequential Write up to 3400MB/s*
Random Read up to 600K IOPS*
Random Write up to 600K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Capacity512GBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6400MB/s*

Sequential Write up to 3400MB/s*
Random Read up to 600K IOPS*
Random Write up to 600K IOPS*

Self-Encrypting Drive OPAL 2

Support

Juppon

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Capacity1TBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read

up to 6500MB/s* **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

Self-Encrypting Drive

Support

OPAL 2

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 TLC SSD

Capacity 1TB **PCIe Protocol Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation Interface

PCI Express 4.0 x4 electrical

Operating Temperature 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6500MB/s* **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS*

Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 TLC SSD

Capacity 1TB **Protocol PCIe Form Factor** M.2 Controller NVMe 3D TLC **NAND Type**

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365 No

operation

PCI Express 4.0 x4 electrical

Interface Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCIe-4x4 SED **OPAL2 TLC M.2 SSD**

2TB Capacity Protocol **PCIe Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

PCI Express 4.0 x4 electrical Interface 32° to 158° F (0° to 70° C) **Operating Temperature**

Nο

Performance Sequential Read up to 6500MB/s*

> **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

Self-Encrypting Drive OPAL 2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCIe-4x4 TLC SSD Capacity 2TB **Protocol PCIe Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

500TBW (TB Written) **Endurance**

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

> **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD

Capacity 4TB **PCIe Protocol Form Factor** M.2 **Controller** NVMe **NAND Type** 3D TLC



^{*}Actual performance may vary.

600TBW (TB Written) **Endurance**

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6500MB/s*

> **Sequential Write** up to 5000MB/s* **Random Read** up to 700K IOPS* up to 700K IOPS* **Random Write**

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

Z Turbo 4TB 2280 PCIe-4x4 SED **OPAL2 TLC M.2 SSD** Capacity 4TB PCIe Protocol **Form Factor** M.2 NVMe Controller **NAND Type** 3D TLC

Endurance 600TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

No

Performance **Sequential Read**

> **Sequential Write** up to 5000MB/s* **Random Read** up to 700K IOPS* up to 700K IOPS*

up to 6500MB/s*

Random Write

Self-Encrypting Drive OPAL 2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

Performance PCIe SSDs for HP Dual Pro Carrier

HP Z Turbo Drive Dual Pro 512GB SSD

Capacity 512GB Protocol **PCIe** M.2 **Form Factor** Controller NVMe **NAND Type** 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

No



^{*}Actual performance may vary.

Performance	Sequential Read	up to 6400MB/s*
	Sequential Write	up to 3400MB/s*
	Random Read	up to 600K IOPS*
	Random Write	up to 600K IOPS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

ΗP	Z	Tui	рo	Driv	e D	ual
Pro	1	TB	SSI	D		

capacity	טוו
Protocol	PCle
Form Factor	M.2
Controller	NVMe
NAND Type	3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365 No

operation Interface

PCI Express 4.0 x4 electrical re 32° to 158° F (0° to 70° C)

Operating Temperature 3
Performance S

Sequential Read up to 6500MB/s*
Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drive	Dua
Pro 2TB SSD	

capacity	218
Protocol	PCIe
Form Factor	M.2
Controller	NVMe
NAND Type	3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drive	Capa
Dual Pro 4TB SSD	Proto
	F

Capacity 4TB
Protocol PCle
Form Factor M.2



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Controller NVMe NAND Type 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

SATA Hard Drives for HP Workstations

1TB 7200RPM SATA 3.5in Capacity Enterprise HDD Protocol

Capacity 1TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability 2.0M hours
Rated Power On Hours 8760/yr
Annualized Failure Rate (based on Rated POH)

Rated for 24/7/365

operation

. Height

Width Media Diameter

Physical Size 4 in; 10.17 cm

3.5 in: 8.9 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

YES

Synchronous Transfer

Rate (Maximum)

Logical Blocks

Up to 600MB/s *

1 in: 2.54 cm

Buffer 128MB Cache Adaptive

Seek Time (typical reads, includes controller overhead, including settling)

Single Track 0.32 ms *

Average 7.45 ms *

Full Stroke 14.2 ms *

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

1,953,525,168

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



^{*}Actual performance may vary.

^{*}Actual performance may vary.

0.7 ms *

8.5 ms *

15.7 ms *

Technical Specifications - Hard Drives

2TB 7200RPM SATA 3.5ii	1
Enterprise HDD	

Capacity 2TB **Protocol** SATA **Form Factor** 3.5" Controller AHCI Reliability 2.0M hours **Rated Power On Hours** 8760/yr Annualized Failure Rate <0.62%

(based on Rated POH)

Rated for 24/7/365

operation

YES

Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm **Physical Size** 4 in: 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 128MB Cache Adaptive

Seek Time (typical reads, Single Track includes controller overhead, including

Rotational Speed

Logical Blocks

settling)

7,200 rpm 3,907,029,168

Average

Full Stroke

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s* **Sequential Write** up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

4TB

4TB 7200 RPM SATA 3.5in Capacity **Enterprise HDD**

Protocol SATA 3.5" **Form Factor** Controller AHCI Reliability 2.0M hours **Rated Power On Hours** 8760/yr **Annualized Failure Rate** <0.62%

(based on Rated POH)

Rated for 24/7/365

operation

YES

Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm **Physical Size** 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s *

Rate (Maximum)

Buffer 256MB



^{*}Actual performance may vary.

Cache Adaptive

Seek Time (typical reads,
includes controller
overhead, includingSingle Track
Average0.7 ms *8.5 ms *Full Stroke15.7 ms *

settling)

Rotational Speed 7,200 rpm **Logical Blocks** 7,814,037,168

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

8TB

8TB 7200RPM SATA 3.5in Capacity Enterprise HDD Protocol

ProtocolSATAForm Factor3.5"ControllerAHCIReliability2.0M hoursRated Power On Hours8760/yrAnnualized Failure Rate<0.62%</th>

(based on Rated POH)

Rated for 24/7/365 YES

operation

Height 1 in; 2.54 cm

WidthMedia Diameter3.5 in; 8.9 cmPhysical Size4 in; 10.17 cm

Up to 600MB/s *

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer 256MB Cache Adaptive

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.7 ms *8.5 ms *
9.7 ms *8.5 ms *Full Stroke15.7 ms *

Rotational Speed 7,200 rpm **Logical Blocks** 15,628,053,168

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

AHCI

12TB 7200 RPM SATA-6G	Capacity	12TB
3.5in Enterprise HDD	Protocol	SATA
	Form Factor	3.5"

Controller

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Reliability 2.0M hours **Rated Power On Hours** 8760/yr **Annualized Failure Rate** <0.62%

(based on Rated POH)

Rated for 24/7/365

operation

Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm

> **Physical Size** 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

YES

Synchronous Transfer

Rate (Maximum)

256MB

Up to 600MB/s *

Buffer Adaptive Cache Seek Time (typical reads, Single Track

includes controller overhead, including settling)

Average 8.5 ms * **Full Stroke** 15.7 ms *

0.7 ms *

Rotational Speed 7,200 rpm **Logical Blocks** 23,437,770,752

Operating Temperature 41° to 140° F (5° to 60° C)

Performance **Sequential Read** up to 226MB/s* **Sequential Write** up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



^{*}Actual performance may vary.

GRAPHICS

NVIDIA® RTX™ 6000 Ada Form Factor

48GB

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1230 grams / 2.71 lbs (with extender)

Max Power Consumption Power: 300 Watts

Cooling: Active

GPU Memory 48GB GDDR6 memory ECC

Memory Bandwidth: Up to 960 GB/s

Memory Width: 384 bits

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

Stereo Sync

Requires CEM 5.0 16-pin auxiliary power adapter

Maximum Resolution 7680x4320 @ 120Hz **Bus Type** PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

NOTE: available in July 2023

NVIDIA® RTX™ A6000

48**GB**

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1230 grams / 2.71 lbs (with extender)

Max Power Consumption Power: 300 Watts

Cooling: Active

48GB GDDR6 memory **GPU Memory**

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink® Stereo Sync

Requires 8-pin auxiliary power

Maximum Resolution 7680x4320 @ 120Hz

Bus Type

PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11

Windows 10

Linux® 64-bit

NVIDIA® RTX™ A5000

24GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

Max Power Consumption Power: 230W

Cooling: Active

GPU Memory 24GB GDDR6 memory

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink® Stereo Svnc

Requires 8-pin auxiliary power

Maximum Resolution

7680x4320 @ 120Hz PCI Express 4.0 x16

Bus Type

Available Graphics Drivers Windows 11 Windows 10

Linux® 64-bit

NVIDIA® RTX A4500 20GB Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

Max Power Consumption Power: 200W

Cooling: Active

GPU Memory 20GB GDDR6 memory

Memory Bandwidth: Up to 640 GB/s

Memory Width: 320 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink® Stereo Sync

Requires 8-pin auxiliary power

Maximum Resolution

Bus Type

7680x4320 @ 120Hz PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® RTX A4000 16GB Form Factor Full-Height Single Slot (4.4" Height x 9.5" Length)

Weight: 500 grams

Max Power Consumption Power: 140W

Cooling: Active

GPU Memory 16GB GDDR6 memory

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

Stereo Sync

Requires 6-pin auxiliary power

Maximum Resolution

7680x4320 @ 120Hz

Available Graphics

Drivers

Bus Type

PCI Express 4.0 x16

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® Long-Life RTX

A4000E 16GB

Form Factor Full-Height Single Slot (4.4" Height

x 9.5" Length) Weight: 500 grams

Max Power Consumption Power: 140W

Cooling: Active



Technical Specifications - Graphics

GPU Memory 16GB GDDR6 memory

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

4x DisplayPort 1.4a **Connectors**

Quadro Sync II connector

Stereo Sync

Requires 6-pin auxiliary power

Maximum Resolution 7680x4320 @ 120Hz

Bus Type PCI Express 4.0 x16

Available Graphics Windows 11 **Drivers** Windows 10

Linux® 64-bit

NOTE: available in June 2023

NVIDIA® RTX A2000 12GB Form Factor Half-Height Dual Slot (2.713"

> Height x 6.6" Length) Weight: 306 grams

Max Power Consumption Power: 70W

Cooling: Active

GPU Memory 12GB GDDR6 memory

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192 bit

Connectors 4x mini-DisplayPort 1.4a **Maximum Resolution** 7680x4320 @ 120Hz **Bus Type** PCI Express 4.0 x16

Available Graphics

Drivers Windows 10

Linux® 64-bit

Windows 11

NVIDIA® Long-Life RTX

A2000E 12GB

Half-Height Dual Slot (2.713" **Form Factor**

> Height x 6.6" Length) Weight: 306 grams

Max Power Consumption Power: 70W

Cooling: Active

GPU Memory 12GB GDDR6 memory

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192 bit

Connectors 4x mini-DisplayPort 1.4a **Maximum Resolution** 7680x4320 @ 120Hz **Bus Type** PCI Express 4.0 x16

Available Graphics

Windows 11 **Drivers**

Windows 10 Linux® 64-bit

NVIDIA® T1000 8GB Form Factor Half-Height Single Slot (2.713"

> Height x 6.137" Length) Weight: 132.6 grams

Technical Specifications - Graphics

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128 bit

Connectors4x mini-DisplayPort 1.4aMaximum Resolution7680x4320 @ 120HzBus TypePCI Express 3.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

NVIDIA® Long-Life T1000E 8GB **Form Factor** Half-Height Single Slot (2.713"

Height x 6.137" Length) Weight: 132.6 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128 bit

Connectors 4x mini-DisplayPort 1.4a
Maximum Resolution 7680x4320 @ 120Hz
Bus Type PCI Express 3.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

NVIDIA® T1000 4GB

Form Factor Half-Height Single Slot (2.713"

Height x 6.137" Length) Weight: 132.6 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128 bit

Connectors 4x mini-DisplayPort 1.4a

Maximum Resolution 7680x4320 @ 120Hz

Bus Type PCI Express 3.0 x16

Available Graphics

Drivers

Windows 11

Windows 10 Linux® 64-bit

NVIDIA® T400 4GB

Form Factor Half-Height Single Slot (2.713" Height x 6.137" Length)

Weight: 123.5 grams

Max Power Consumption Power: 30W

Cooling: Active

Technical Specifications - Graphics

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Up to 80 GB/s

Memory Width: 64 bit

Connectors 3x mini-DisplayPort 1.4a
Maximum Resolution 7680x4320 @ 120Hz
Bus Type PCI Express 3.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

AMD® Radeon™ Pro W6800 32GB **Form Factor** Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 850 grams

Max Power Consumption Power: 261W

Cooling: Active

GPU Memory 32GB GDDR6 memory

Memory Bandwidth: Up to 512 GB/s

Memory Width: 256 bit

Connectors 6x mini-DisplayPort 1.4

Requires 8-pin+6-pin auxiliary power

Maximum Resolution7680x4320 @ 60HzBus TypePCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

AMD® Radeon™ Pro W6600 8GB **Form Factor** Full-Height Single Slot (4.38" Height x 9.50" Length)

Weight: 132.6 grams

Max Power Consumption Power: 122W

Cooling: Active

GPU Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 224 GB/s

Memory Width: 128 bit

Connectors 4x DisplayPort 1.4

Requires 6-pin auxiliary power

Maximum Resolution 7680x4320 @ 60Hz

Bus Type PCI Express 4.0 x16 (x8 electrical)

Available Graphics

Form Factor

Drivers Windows 10

Linux® 64-bit

Windows 11

AMD® Radeon™ RX 6400

4GB

Half-Height Single Slot (4.4" Height x 10.5" Length)

Weight: 155 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Memory Width:

Technical Specifications - Graphics

Connectors 1x DisplayPort 1.4a

1x HDMI

Maximum Resolution 7680x4320 @ 60Hz **Bus Type** PCI Express 4.0 x4 Windows 11

Available Graphics

Drivers Windows 10

Linux® 64-bit

Intel® Arc Pro A40 6GB **Form Factor** Half-Height Single Slot (2.7" Height x 6.6" Length)

Weight: 220 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 4GB GDDR6 memory

> Memory Bandwidth: 192GB Memory Width: 96 bit

Connectors 4x mini- DisplayPort 1.4 **Maximum Resolution** 7680x4320 @ 60Hz **Bus Type** PCI Express 4.0 x8

Available Graphics Windows 11 **Drivers** Windows 10

NOTE: available in July 2023

Notes for all graphics cards:

- Some graphics and GPU compute cards can consume a great deal of power, thus combinations of cards with other components may exceed a particular power supply's output capability.
- Some graphics and GPU compute cards require supplemental power cables.
- Not all chassis/PSU configurations have enough supplemental power cables of the correct type for all graphics configurations.

Refer to the Power Supply section within Overview for more information.

OPTICAL AND REMOVABLE STORAGE

HP 9.5mm Slim Blu-Ray Writer

Description 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types BD-ROM

> BD-R BD-RE DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW



CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

> 25 GB (single-layer) Blu-ray

50 GB (dual-layer) 100/128 GB (BDXL)

Full Stroke DVD < 230 ms (seek) Full Stroke CD < 220 ms (seek)

Blu-ray < 230 ms (seek) (Full Stroke Blu-ray) **Startup Time** (Time to drive ready from tray loading)

> BD-ROM (SL/DL) 255 / 285 255 / 285 BD-R (SL/DL) BD-RE (SL/DL) 255 / 285 DVD-ROM (SL/DL) 185 / 185 DVD-R (SL/DL) 25S / 25S

DVD-RW **25S**

DVD+R (SL/DL) 25S / 25S

DVD+RW **25S** CD-ROM **15S**

Maximum Data Transfer CD ROM Read

Rates

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Blu-ray BD-ROM Up to 6X

> BD-ROM DL Up to 6X BD-R Up to 6X BD-R DL Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X

Power Source SATA DC power receptacle

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p 5 VDC -900 mA typical, 2000mA **DC Current**

maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

condensing)

Relative Humidity 10% to 80% **Maximum Wet Bulb** 84° F (29° C)

Temperature

Operating Systems Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit, Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation

SUSE Linux® Enterprise Desktop 15

Ubuntu 20.04, 22.04 LTS

No driver is required for this device. Native support is provided by the

operating system.



Kit Contents 9.5mm Slim BDXL Blu-Ray Writer, 5.25" ODD Bay adapter/carrier, slim

SATA data/power cable, installation guide

As Blu-ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

NOTE: HD-DVD disks cannot be played on the DVD-ROM drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players. Flawless playback on all systems is not guaranteed.

HP 9.5mm Slim DVD Writer **Description** 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types

DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

DVD+R

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Full Stroke DVD < 200 ms (seek)
Full Stroke CD < 200 ms (seek)

Maximum Data Transfer

Rates

CD ROM Read CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

condensing)

Relative Humidity 10% to 80% Maximum Wet Bulb 84° F (29° C)

Temperature

Operating Systems

Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit,

Windows Vista Business 64*, Windows 2000.

Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation

SUSE Linux® Enterprise Desktop 15 Ubuntu 20.04. 22.04 LTS

* No driver is required for this device. Native support is provided by the operating system

Kit Contents HP SATA DVD Writer drive, installation guide.

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

HP 9.5mm Slim DVD-ROM Description 9.5mm height, tray-load

Mounting Orientation Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

Access Times DVD-ROM Single Layer < 110 ms (typical)

> **CD-ROM Mode 1** < 110 ms (typical) **Full Stroke DVD** < 230 ms (typical) **Full Stroke CD** < 220 ms (typical)

Power SATA DC power receptacle Source

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum 41° to 122° F (5° to 50° C)

Operating Environmental Temperature

(all conditions non-

condensing)

Relative Humidity 10% to 80% **Maximum Wet Bulb** 84° F (29° C)

Temperature

Operating Systems **Supported**

Windows 11, Windows 10, Windows 8.1, Windows 7 Professional 64-bit

Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation

SUSE Linux® Enterprise Desktop 15

Ubuntu 20.04, 22.04 LTS

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim DVD-ROM Drive, 5.25" ODD Bay adapter/carrier, slim SATA

data/power cable, installation quide

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

NVIDIA® Mellanox® Connect ConnectX-6 DX Dual Port Cabling 10/25GbE SFP28 NIC

Connector 2 x SFP28 Transceiver Cage (Dual Port)*

Cabling Depends on transceiver pairing. Typically OM4 or higher MMF LC fiber optic

cabling with LC SFP28 Transceivers.

Controller ConnectX6-DX

Memory 256Mbit SPI Quad Flash Device

Data Rates Supported 1/10/25GbE

Compliance – IEEE 802.3by 25 Gigabit Ethernet – IEEE 802.3ae 10 Gigabit Ethernet

- IEEE 802.3ap based auto-negotiation and KR startup

- IEEE 802.3ad, 802.1AX Link Aggregation - IEEE 802.1Q, 802.1P VLAN tags and priority

IEEE 802.1Qau (QCN)
Congestion Notification
IEEE 802.1Qaz (ETS)
IEEE 802.1Qbb (PFC)
IEEE 802.1Qbg
IEEE 1588v2

Jumbo frame support (9.6KB)Safety: CB/cTUVus/CEEMC: CE/FCC/VCCI/RCMRoHS Compliant

- KCC

- CAN ICES-3 (B)

- NM EN 55035/55032 (Morocco)

UKCA

Bus Architecture PCIe Gen 4 x8

Data Transfer Mode PCI Express - stores and accesses Ethernet fabric connection information

and packet data

Power Requirements 11.5 Watts (typical) **Network Transfer Rate** 1Gbps, 10Gbps, 25Gbps

NOTE: Network Transfer Rate depends on transceiver model.*

Kit Contents NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC

*3rd party transceivers sold separately. You must have a transceiver installed in order to connect this card to a network.

Intel® X550 10GBASE-T Dual Port NIC **Connector** 2 x RJ-45

Cabling Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps Cat6 (or higher) for 10Gbps up to 55m Cat6a (or higher) for 10Gbps up to 100m

Controller Intel X550-AT2

Memory Jumbo Frames up to 15.5KB, 64 Tx and 64Rx Queues per port, 160KB/port

of programmable memory transmit buffers

Data Rates Supported 100Mbps (BASE-TX), 1Gbps (BASE-T, 2.5Gbps, 5Gbps, 10Gbps

Compliance 802.1q (VLAN), 802.1Qbb, 802.1p, 802.1Qaz

Technical Specifications - Networking and Communications

Bus Architecture PCle 3x4

Data Transfer Mode PCle Gen 3 x4 based interface

Power Requirements 3.9W at 100Mbps

5.5W at 1Gbps 11.2W at 10Gbps

Boot ROM Support Yes

Network Transfer Mode Auto negotiation between 1GbE, 2.5GbE, 5GbE and 10GbE

Management Capabilities DMI 2.0 Support, Windows Management Instrumentation (WMI) and SNMP.

PXE 2.0 through boot ROM, Multi-mode I/O Virtualization, VxLAN, VMDq,

VLAN support with VLAN tag insertion

Kit Contents Intel® X550 10GBASE-T Dual Port NIC

Intel® 1225-T1 Single Port 2.5GbE PCIe NIC **Connector** RJ-45 (Single Port)

Cabling Cat5e (or better) up to 100m **Controller** Intel® Ethernet I225 Controller

Memory Jumbo Frames up to 9.5KB, 4 Tx and Rx Queues,

Data Rates Supported 2.5GbE, 1GbE, 100MbE, 10MbE

Compliance IEEE 802.3 auto negotiation, 802.3x, 802.3z

Bus Architecture PCle Gen 3.1x1

Data Transfer Mode PCIe-based interface for active state operation

Power Requirements 1.9 Watts (typical)

Management Capabilities WOL, PXE 2.1, Power Management Protocol Offload (proxying), MAC Power

Management, Active State Power Management.

Kit Contents Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracket attached

and Low-profile bracket included

Product Literature

Intel® Ethernet I350-T4V2 4-Port 1Gb NIC

Connector 4x RJ-45 (Quad Port)

Cabling Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps

cats (of fligher) for roombps

Cat5e (or higher) for 1Gbps up to 100m

Controller Intel® I350

Memory Jumbo Frames up to 9.5KB, 8 Tx/Rx Queue pairs per port, Main Internal

memory is Error Code Correcting

Data Rates Supported 10Mbps, 100Mbps, 1Gbps

Compliance IEEE 802.3 auto negotiation.

IEEE 802.3 auto negotiation, 802.3, 802.3u, 802.3ab, 802.3x, 802.3z,

IEEE1588 protocol and 802.1AS implementation, 802.3az EEE

Bus Architecture PCI Express 2.1 x4

Data Transfer Mode PCIe-based interface for active state operation

Power Requirements 5W

Network Transfer Mode Multi-speed, full, and half-duplex

Network Transfer Rate 10BASE-T

100BASE-Tx 1000BASE-T

Management Capabilities WOL, PXE 2.1, UEFI, Power Management Protocol Offload (proxying), MAC

Power Management, Active State Power Management, VLAN, ACPI

Technical Specifications - Networking and Communications

Cabling

Kit Contents Intel® Ethernet I350-T4V2 4-Port 1Gb NIC with full-height bracket installed

Low-profile bracket included

Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC **Connector** 2 x RJ-45 (Dual Port)

Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps up to 100m

Memory 17 Rx and 16 Tx queues

Data Rates Supported 10/100/1000 Mbps

Compliance IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC),

IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation), IEEE 802.3ab

(10/100/1000T)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Bus Architecture PCle 2x1

Data Transfer ModePCIe-based interfacePower Requirements2.4 Watts (typical)

Management Capabilities VLAN support, Link aggregation LACP, Link aggregation smart switch,

Failover, Smart Load Balancing (SLB), iSCSI boot support, Windows

Management Instrumentation (WMI), PXE 2.1, SNMP

Kit Contents Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC with low-profile bracket

attached and standard bracket included

Allies Telesis AT-2914SX/LC 1GB LC Fiber NIC **Connector** LC Fiber (Single Port)

Cabling 50/125 μm (core/cladding) multimode fiber optic cable up to 500m

62.5/125 µm (core/cladding) multimode fiber optic cable up to 220m

Memory Jumbo Frames up to 9.6KB

Data Rates Supported

1000SX (1GbE Fiber at 850nm Wavelength)

Compliance

IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANS), IEEE 802.2 (LLC), IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE

802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Bus Architecture PCle x1

Data Transfer Mode PCle-based interface **Power Requirements** 1.5 Watts (typical)

Network Transfer Rate 1000SX only (1GbE Fiber at 850nm Wavelength)

Management Capabilities UEFI, Smart Load Balancing and failover, Link aggregation (IEEE802.3ad),

Generic trunking (FEC/GEC) / IEEE 802.3ad-draft static, VLAN Support

Kit Contents Allied Telesis AT-2914SX/LC 1GB LC Fiber NIC with low-profile bracket

attached and standard height bracket included

Intel® AX210 Wi-Fi 6E non-vPro + Bluetooth® 5.2 with External Antennae WLAN Connector Wireless
Cabling N/A

Controller Intel® AX210

Data Rates Supported Wi-Fi 6e (2.4GHz/5GHz/6GHz)

Technical Specifications - Networking and Communications

Compliance Wi-Fi Alliance* Wi-Fi Alliance CERTIFIED 6, WiFi CERTIFIED a/b/g/n/ac,

WMM, WMM-Power Save, WPA2, WPA3, Wi-Fi Direct, and Wi-Fi Agile

Multiband

IEEE WLAN Standard 802.11-2016, 802.11a, b, d, e, g, h, l, k, n, r, u, v, w, ac,

and ax, Bluetooth® 5.2

Bus Architecture PCIe G3x1 for WLAN, USB3.1G1 for BT

Management Capabilities Authentication Protocols: 802.1X EAP-TLS, EAP-TTLS/MSCHAPv2, PEAPv0 -

MSCHAPv2 (EAP-SIM, EAP-AKA, EAP-AKA')

Encryption: 128-bit AES-CCMP, 256-bit AES-GCMP

UEFI

Kit Contents Intel® AX210 Wi-Fi 6 + Bluetooth® 5.2 PCIe NIC

External Dipole Antenna Installation Instructions

*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available

in countries where Wi-Fi 6E is supported.

Date of change:	Version History:		Description of change:
March 1, 2023	From v1 to v2	Changed	Optical and Removable Storage, Networking and Communications sections and Changed Format



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